

## ***Dow Corning®* SE 9186 Clear or White Adhesive**

### **FEATURES & BENEFITS**

- Fast tack-free room temperature cure
- Flowable
- Controlled silicone volatility
- Cures to soft, low stress elastomer
- No added solvents
- No mixing required
- Room temperature cure, no ovens required
- Faster in-line processing at room temperature with option for heat acceleration
- Able to flow, fill or self-leveling after dispensing
- Reduced potential for silicone volatiles

### **COMPOSITION**

- One-part, translucent or white
- Polydimethylsiloxane

One-part, translucent or white, flowable, fast tack-free, controlled volatility adhesive

### **APPLICATIONS**

*Dow Corning®* SE 9186 Clear or White Adhesive is suitable for:

- Sealing of electronic equipment and modules
- Parts fixing on circuit board
- Sealing against potential stress cracks

### **TYPICAL PROPERTIES**

Specification Writers: These values are not intended for use in preparing specifications. Please contact your local Dow Corning sales office or your Global Dow Corning Connection before writing specifications on this product.

| Property                                                              | Unit               | Result               |
|-----------------------------------------------------------------------|--------------------|----------------------|
| One or Two-part                                                       | -                  | One                  |
| Color                                                                 | -                  | Translucent or White |
| Viscosity                                                             | cP                 | 64000                |
|                                                                       | Pa-sec             | 64                   |
| Specific Gravity (Cured)                                              | -                  | 1.03                 |
| Tack Free Time at 25 °C                                               | minutes            | 8                    |
| Tensile Strength                                                      | psi                | 360                  |
|                                                                       | MPa                | 2.5                  |
|                                                                       | kg/cm <sup>2</sup> | 25                   |
| Elongation                                                            | %                  | 550                  |
| Durometer Shore A                                                     | -                  | 20                   |
| Adhesion Lap Shear (glass)                                            | psi                | 185                  |
|                                                                       | MPa                | 1.3                  |
|                                                                       | N/cm <sup>2</sup>  | 130                  |
| Dielectric Strength                                                   | volts/mil          | 575                  |
|                                                                       | kV/mm              | 23                   |
| Volume Resistivity                                                    | ohm*cm             | 2.0E +16             |
| Content of Low Molecular Siloxane (D4-D10) Translucent/White version  | ppm                | 35/45                |
| Content of Low Molecular Siloxane (D4-D20): Translucent/White version | ppm                | 230/300              |

## DESCRIPTION

*Dow Corning*<sup>®</sup> brand one-part moisture cure adhesives are generally cured at room temperature and in an environment of 30 to 80 percent relative humidity eliminating the need for curing ovens and the associated costs of energy and capital. Greater than 90 percent of full physical properties should be attained within 24 to 72 hours and varies according to product. Faster manufacturing throughput can be achieved since the adhesive and component can be handled in much shorter times of about 10 to 120 minutes, depending on the adhesive selected and the amount applied. These adhesives are not typically used in highly confined spaces or where a deep section cure is required as they generally cure from the exposed surface inward at a rate of 0.25 inch per seven days. Cure progresses from the outer exposed surface and is dependent on the moisture in the air. Working time is generally a few minutes to an hour for these products until a surface skin begins to form. Mild heat below 60°C (140°F) may be used to increase through-put by accelerating the cure. *Dow Corning* brand silicone adhesives retain their original physical and electrical properties over a broad range of operating conditions which enhance the reliability of and service life of electronic devices. The stable chemistry and versatile processing options of these adhesives offer benefits for a variety of electronics needs from increasing component safety and reliability, reducing total cost or increasing the performance envelope of devices or modules.

## APPLICATION METHODS

- Simple needle dispensing systems
- Automated systems are normally used for high volume processes
- Manual dispensing for low volumes

## PACKAGING INFORMATION

Multiple packaging sizes are available for this product. Please contact your

local distributor or Dow Corning representative for information on packaging size and availability.

## USABLE LIFE AND STORAGE

For best results, *Dow Corning* RTV adhesives should be stored at or below the storage temperature listed on the product label. Special precautions must be taken to prevent moisture from contacting these materials. Containers should be kept tightly closed with head or air space minimized. Partially filled containers should be purged with dry air or other gases, such as nitrogen. The product should be stored in its original packaging with the cover tightly attached to avoid any contamination. Store in accordance with any special instructions listed on the product label. The product should be used by its Use Before date as indicated on the product label.

## PREPARING SURFACES

All surfaces should be thoroughly cleaned and/or degreased with *Dow Corning*<sup>®</sup> brand OS Fluids, naphtha, mineral spirits, methyl ethyl ketone (MEK) or other suitable solvent. Solvents such as acetone or isopropyl alcohol (IPA) do not tend to remove oils well, and any oils remaining on the surface may interfere with adhesion. Light surface abrasion is recommended whenever possible, because it promotes good cleaning and increases the surface area for bonding. A final surface wipe with acetone or IPA is also useful. Some cleaning techniques may provide better results than others; users should determine the best techniques for their particular applications.

## SUBSTRATE TESTING

Due to the wide variety of substrate types and differences in substrate surface conditions, general statements on adhesion and bond strength are impossible. To ensure maximum bond strength on a particular substrate, cohesive failure of the product in a lap shear or similar test is needed to

ensure compatibility of the adhesive with the substrate being considered. Also, this test can be used to determine minimum cure time or to detect the presence of surface contaminants such as mold release agents, oils, greases and oxide films.

## ADHESION

*Dow Corning* adhesives are specially formulated to provide unprimed adhesion to many reactive metals, ceramics and glass, as well as to selected laminates, resins and plastics. However, good adhesion cannot be expected on non-reactive metal substrates or non-reactive plastic surfaces such as Teflon<sup>®</sup>, polyethylene or polypropylene. Special surface treatments such as chemical etching or plasma treatment can sometimes provide a reactive surface and promote adhesion to these types of substrates. *Dow Corning*<sup>®</sup> brand primers can be used to increase the chemical activity on difficult substrates. Poor adhesion may be experienced on plastic or rubber substrates that are highly plasticized, because the mobile plasticizers act as release agents. Small-scale laboratory evaluation of all substrates is recommended before production trials are made.

## USEFUL TEMPERATURE RANGES

For most uses, silicone adhesives should be operational over a temperature range of -45 to 200°C (-49 to 392°F) for long periods of time. However, at both the low- and high temperature ends of the spectrum, behavior of the materials and performance in particular applications can become more complex and require additional considerations. For low-temperature performance, thermal cycling to conditions such as -55°C (-67°F) may be possible, but performance should be verified for your parts or assemblies. Factors that may influence performance are configuration and stress sensitivity of components, cooling rates and hold times, and prior temperature history. At the high-

temperature end, the durability of the cured silicone elastomer is time and temperature dependent. As expected, the higher the temperature, the shorter the time the material will remain useable.

## **SOLVENT EXPOSURE**

The silicone adhesive discussed in this literature is intended only to survive splash or intermittent exposures. It is not suited for continuous solvent or fuel exposure. Testing should be done to confirm performance of the adhesives under these conditions.

## **HANDLING**

### **PRECAUTIONS**

#### **PRODUCT SAFETY**

**INFORMATION REQUIRED FOR SAFE USE IS NOT INCLUDED IN THIS DOCUMENT. BEFORE HANDLING, READ PRODUCT AND MATERIAL SAFETY DATA SHEETS AND CONTAINER LABELS FOR SAFE USE, PHYSICAL AND HEALTH HAZARD INFORMATION. THE MATERIAL SAFETY DATA SHEET IS AVAILABLE ON THE DOW CORNING WEBSITE AT DOW CORNING.COM, OR FROM YOUR DOW CORNING SALES APPLICATION ENGINEER, OR DISTRIBUTOR, OR BY CALLING DOW CORNING CUSTOMER SERVICE.**

## **LIMITATIONS**

This product is neither tested nor represented as suitable for medical or pharmaceutical uses.

## **HEALTH AND ENVIRONMENTAL INFORMATION**

To support customers in their product safety needs, Dow Corning has an extensive Product Stewardship organization and a team of Product Safety and Regulatory Compliance (PS&RC) specialists available in each area.

For further information, please see our website, [dowcorning.com](http://dowcorning.com) or consult your local Dow Corning representative.

## **LIMITED WARRANTY INFORMATION – PLEASE READ CAREFULLY**

The information contained herein is offered in good faith and is believed to be accurate. However, because conditions and methods of use of our products are beyond our control, this information should not be used in substitution for customers' tests to ensure that our products are safe, effective, and fully satisfactory for the intended end use. Suggestions of use shall not be taken as inducements to infringe any patent.

Dow Corning's sole warranty is that our products will meet the sales specifications in effect at the time of shipment.

Your exclusive remedy for breach of such warranty is limited to refund of purchase price or replacement of any product shown to be other than as warranted.

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## **HOW CAN WE HELP YOU TODAY?**

Tell us about your performance, design and manufacturing challenges. Let us put our silicon-based materials expertise, application knowledge and processing experience to work for you.

**For more information** about our materials and capabilities, visit **[dowcorning.com](http://dowcorning.com)**.

To discuss how we could work together to meet your specific needs, email [electronics@dowcorning.com](mailto:electronics@dowcorning.com) or go to [dowcorning.com/contactus](http://dowcorning.com/contactus) for a contact close to your location. Dow Corning has customer service teams, science and technology centers, application support teams, sales offices and manufacturing sites around the globe.

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